IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Divisional Patent Application of:	)	
Kenshi KANEGAE et al.	)	Examiner: Kin Chan Chen
Based on Serial No. 09/837,556	)	Group Art Unit: 1765
Filed: April 19, 2001	)	
For: ETCHING METHOD, SEMICONDUCTOR AND FABRICATING METHOD FOR THE SAME	)))	Date: October 7, 2003

PRELIMINARY AMENDMENT

Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please amend the above identified application as follows:

IN THE SPECIFICATION:

Please amend the specification as follows:

Page 39, Paragraph 9, continuing on Page 40

FIGS. **20(a)** through **20(c)** are cross-sectional views of process steps of the fabricating method for a semiconductor device of the eighth embodiment of the present invention.

Page 85, Paragraph 2

A semiconductor device and a fabricating method therefor of the eighth embodiment will be described with references to FIGS. **19(a)** to **19(c)** and **20(a)** to **20(c)**.